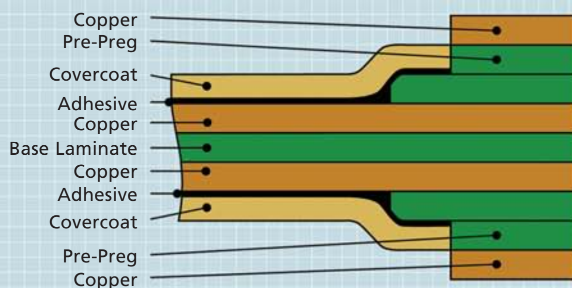
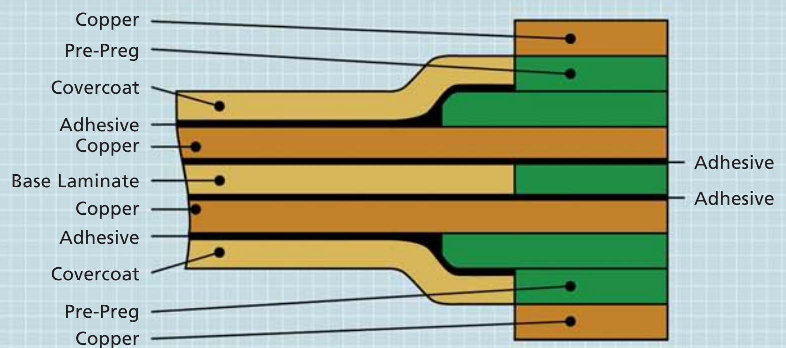
REGAL Flex™

The ultimate solution for flex rigid multilayer

REGAL™ One Multilayer Circuit Construction



REGAL™ Five Multilayer Circuit Construction



General Description

The REGAL Flex™ technology achieves a flex-rigid board that is thermally stable with ultra-high density. The process completely eliminates all polyimide films and acrylic adhesive in the rigid areas, thus reducing the influence of these materials on the overall coefficient of expansion (CTE) and yielding extended reliability over standard constructions.

Materials

REGAL™ Flex constructions eliminate the high coefficient of thermal expansion (CTE) flex adhesives and dielectrics from the rigid areas leaving only the high glass transition temperature (Tg), low CTE, high specification pre-preg in the rigid areas.

The flex laminates and coverfilms are only employed where required in the flex limbs. This combination of materials and construction provides optimum benefits for the product during assembly and during use in terms of thermal and flexural performance. Circuit boards manufactured using REGAL™ Flex techniques exceed military, aerospace and commercial specifications for flex-to-install applications.

Benefits

REGAL™ Flex as an alternative flex-rigid multilayer technology encompasses all of the benefits of a flex-rigid multilayer but has the following added advantages:

- High thermal stability
- Enhanced reliability
- Very high layer count capability

REGAL™ One

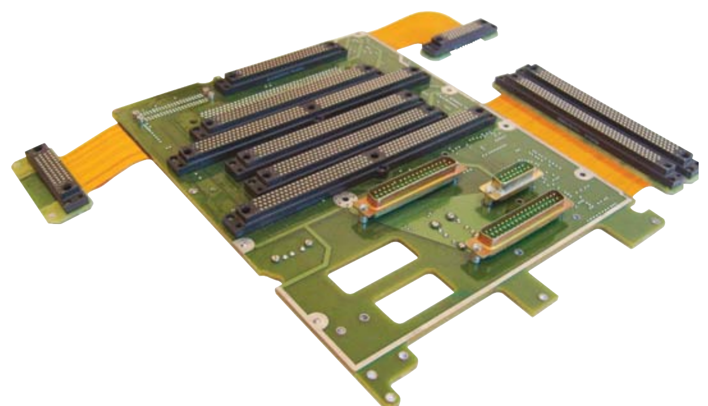
- Flex to install applications
- Higher volume
- Cost competitive
- Highly stable

REGAL™ Five

- Where greater flexibility is required with thin single-sided balanced circuit layers
- Lower weight
- Lower thickness/profile

(Lower weight and Lower thickness/profile: 10-15% improvement on standard)

- High performance
- Highly stable



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